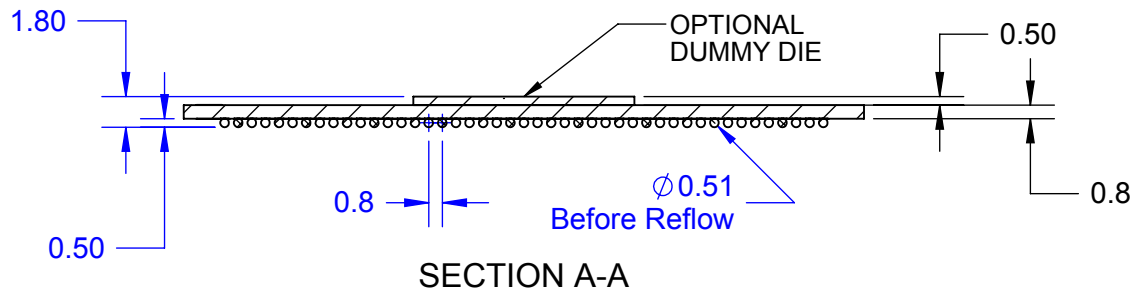
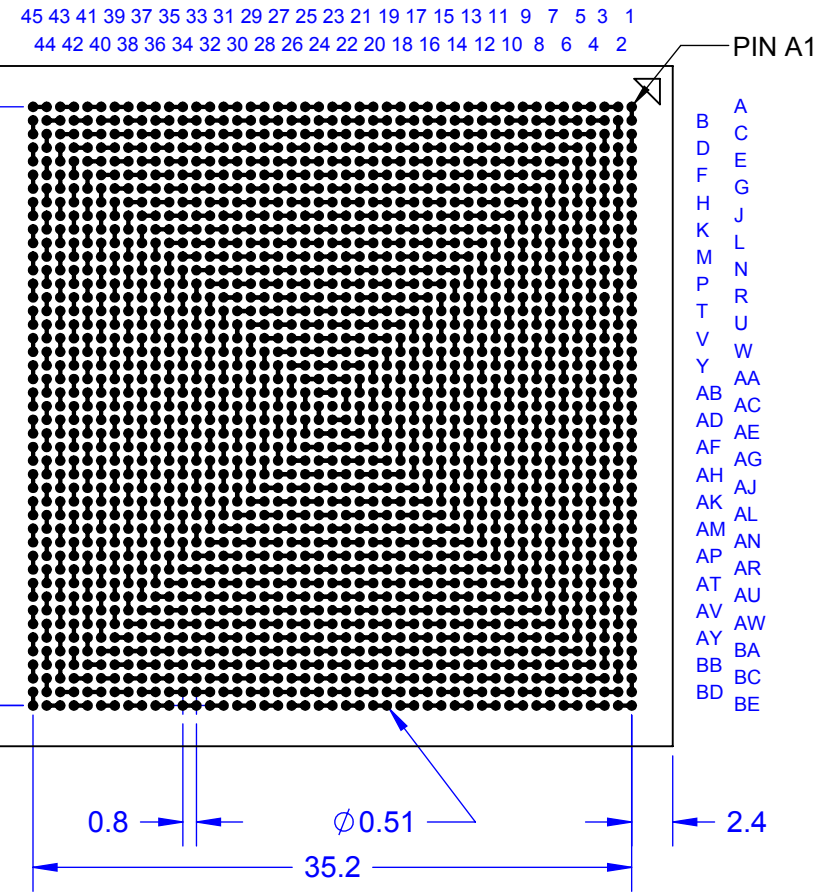
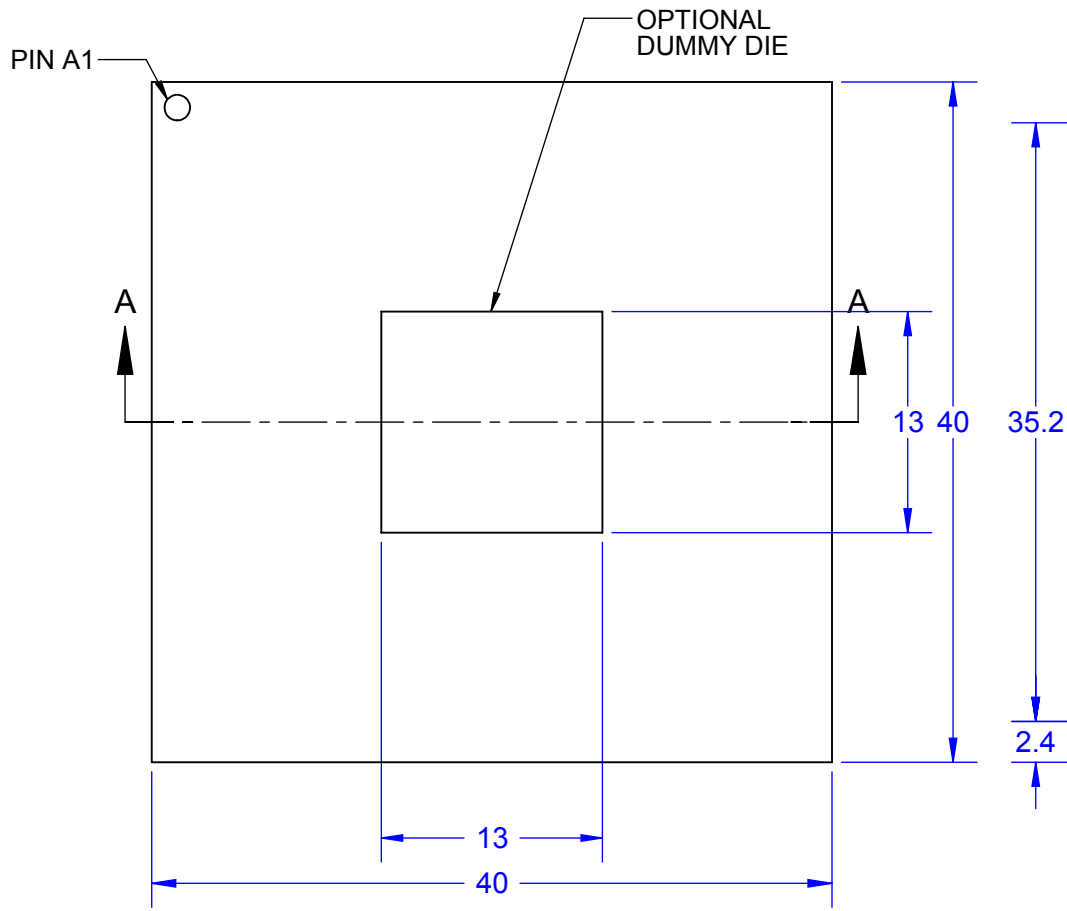


TOP VIEW

BALL VIEW



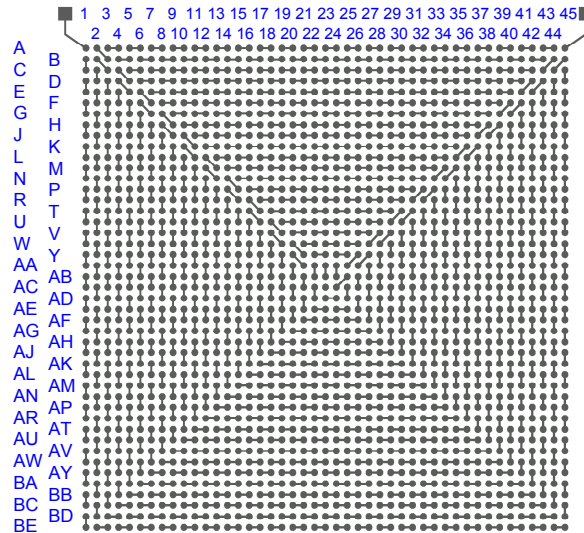
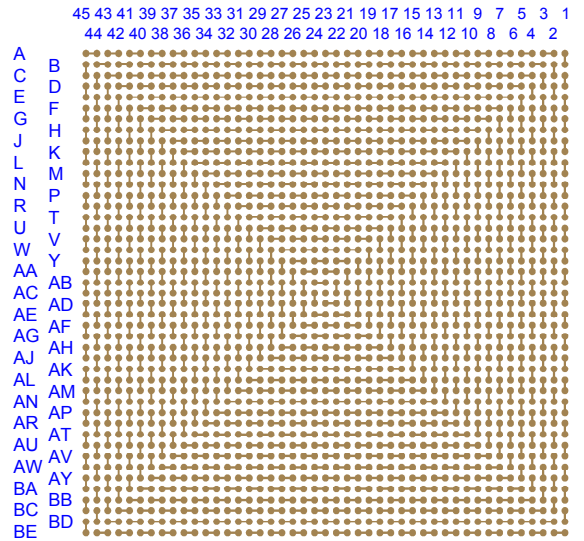
- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
  - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
  - 3) BALL DIAMETER (BEFORE REFLOW): 0.51mm (20 MIL).
  - 4) SOLDER MASK DEFINED PAD OPENING: 0.447mm (17.6 MIL).
  - 5) PAD Cu DIAMETER: 0.558mm (22 MIL).
  - 6) SUBSTRATE MATERIAL: BT HL832NS (OSP Finish).
  - 7) DUMMY DIE 13x13mm (Size OPTIONAL).
  - 8) DAISY CHAIN PATTERN (SEE PAGE 2).
  - 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

PART NUMBER TABLE

PART NUMBER	BALL ALLOY	Pb-Free	RoHS	Si DIE
LBGA2025T.8C-DC459D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LBGA2025T.8-DC459D	Sn63/Pb37	NO	NO	YES

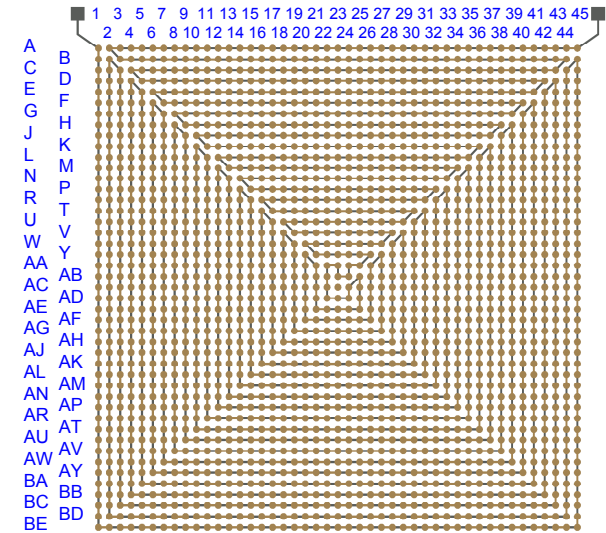
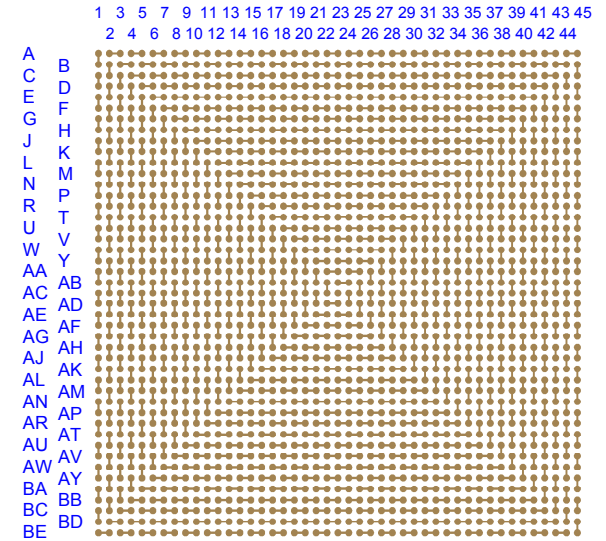
APPROVALS	DATE	<b>TopLine®</b>		
DRAWN T.Au	09/19/13			
ENG M. Hart	09/19/13	TITLE		LBGA2025T.8C-DC459D DAISY CHAIN DUMMY
MFG		SCALE	SIZE	DRAWING NO.
QA		2:1	A	584591
CUST				REV A
REVISED		DO NOT SCALE DRAWING		SHEET 1 OF 2

### BALL VIEW



### TEST VEHICLE BOARD

### BOTTOM SIDE (TOP X-RAY VIEW)



### AFTER MONTING

**Notes:**

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.51mm (20 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.447mm (17.6 MIL).

<b>TopLine®</b>			
TITLE		LBGA2025T.8C-DC459D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
1.8:1	A	584591	A
DO NOT SCALE DRAWING			SHEET 2 OF 2